Easy to use mid-size vertical type push switch





Typical Specifications

Items	Specifications		
Rating (max.)/(min.) (Resistive load)	0.1A 30V DC / 50μA 3V DC		
Contact resistance (Initial performance)	100mΩ max.		
Operating force	2±1N		
Operating life with load	10,000 cycles (0.1A 30V DC)		

Product Line

Changeover	Travel	Travel (mm) Total travel Mounting method Poles Operation Termina type		Poles	Oneration	Terminal Location		ration Terminal	Location lug	Minimum ord	er unit (pcs.)	Product No.
timing	(mm)		type	Japan	Export	1 1000001100.						
Non shorting	2.2	2.2 3 [PC board	2	Latching		With			SPPH410100		
					Momentary Straight	VVILII			SPPH410200			
					2 Latching		Without	100	6,000	SPPH420100		
						Snap-in	With			SPPH430100		
					Momentary	oriap-III	VVILII			SPPH430200		

Packing Specifications

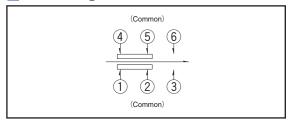
Bulk

Number of pa	ckages (pcs.)	Export package measurements		
1 case / Japan 1 case / export packing		(mm)		
1,200	6,000	400×270×290		

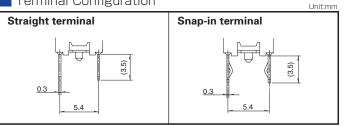
Dimensions PC board mounting hole dimensions (Viewed from the direction A) Style With boss (0.2) 6-ø0.9 hole Thickness of PC board t=1.6mm Terminal No.2 Location lug Terminal No.1

Note Dimensions drawing is for type with location lugs.

■ Circuit Diagram (Viewed from Direction A)



■ Terminal Configuration



			Vertical								
Series		SPEH	SPEG	SPEJ	SPPH2	SPPH4	SPPH1				
Photo											
		W	6	7.19	7	6	6.5	10			
Dimensio (mm)			6	8.39	7	6.5	8.5	10			
	Н		5	3.5	5.95	6.5 8.5		.5			
Tra	vel (mm))	_	_	1.7	1	2.2	1.5			
Total	travel (m	ım)	1.6	1.1	1.7	1.5	3	2.5			
Numb	per of pol	es	1	1	2		2				
	perating rature ra	nge	-40℃ to +90℃	-10°C to +60°C	-40℃ to +85℃		-10°C to +60°C				
Auto	motive u	se	•	_	•	_	_	•			
Li	fe cycle		* 3	* 3	*3	*3		* 3			
	ng (max istive loa		50mA 16V DC	1mA 5V DC	0.2A 14V DC	0.1A 12V DC 0.1A 30V		OV DC			
	ing (min. istive loa		10μA 1V DC	50μA 3V DC	_	50μA 3V DC					
D. white	Durability Operating life without load Operating life with load (at max. rated load)		100,000 cycles 400mΩ max.	30,000 cycles 500mΩ max.	10,000 cycles 150mΩ max.	10,000 cycles 50mΩ max.	10,000 cycles 100mΩ max.	10,000 cycles 40mΩ max.			
Durability			100,000 cycles 400mΩ max.	30,000 cycles 500mΩ max.	10,000 cycles 150mΩ max.	10,000 cycles 50mΩ max.	10,000 cycles 100mΩ max.	10,000 cycles 40mΩ max.			
		contact tance	200mΩ max.	200mΩ max.	150mΩ max.	30mΩ max.	100mΩ max.	20mΩ max.			
Electrical performance		lation tance	100MΩ min. 100V DC	3MΩ min. 100V DC	100MΩ min. 500V DC	100MΩ min. 500V DC)C			
	Voltag	ge proof	250V AC for 1minute	100V AC for 1minute	500V AC for 1minute	Ę	500V AC for 1minut	lminute			
		minal ength	_	0.5N for 1minute	_	5N for 1minute					
Mechanical performance	Actuator strength	Operating direction	50	DN	49N	30	ON	50N			
			_	_	_	_	10N	_			
	Cold		-40°C 1,000h	-20°C 96h	-40℃ 500h	-20°C 96h					
Environmental performance	Dry heat		90°C 1,000h	85℃ 96h	85°C 500h	85°C 96h					
	Damı	o heat	60°C, 90 to 95% RH 1,000h	40°C, 90 to 95% RH 96h	60°C, 90 to 95% RH 500h	40°C, 90 to 95%RH 96h					
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Note

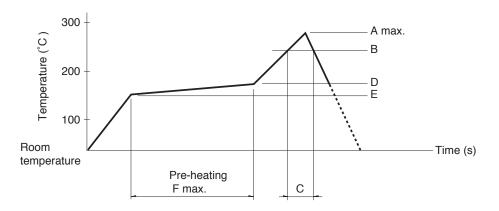
• Indicates applicability to all products in the series.



Push Switches Soldering Conditions

Example of Reflow Soldering Condition

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.
- 3. Temperature profile



Series (Reflow type)	A (℃) 3s max.	B (℃)	C (s)	D (°C)	E (℃)	F(s)
SPEG						
SPEJ	260	230	40	180	150	120
SPEF						
SPEH						

Notes

- 1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
- 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

Series	Soldering temperature	Soldering time	
SPPJ3, SPPJ2, SPUN, SPPH4, SPPH1	350±10℃	3+1/0s	
SPED2, SPED4	350±10℃	3±0.5s	
SPEJ	350±10°C	4s max.	
SPEG, SPEF	350±5℃	3s max.	
SPEH, SPPH2	350°C max.	3s max.	
SPUJ	300±10°C	3+1/0s	

Reference for Dip Soldering (For PC board terminal types)

Series	Ite	ms	Dip soldering		
Jelles	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion	
SPPJ3	100℃ max.	60s max.	260±5℃	5±1s	
SPUN	100℃ max.	60s max.	260±5℃	10±1s	
SPUJ, SPPH2, SPPH4	_		260±5℃	5±1s	
SPPJ2, SPPH1, SPED2, SPED4, SPEF	_		260±5℃	10±1s	

